

AMENDMENT TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-21 (Canceled).

22. (Currently Amended) A workpiece carrier for holding a plurality of pre-diced and essentially rotationally symmetric substrates during processing of a substrate surface, comprising:

a holder configured to hold the plurality of substrates while they are positioned;

a handling element; and

a base element configured to hold one of the substrates and positioned on the handling element, ~~process-dependent covering elements being assignable to a side of the base element opposite the handling element~~, the positioning of the substrate fixed by a holding of a rotational position of the substrate; and

at least two process-step-dependent covering elements, wherein a first process-step-dependent covering element is assigned to a side of the base element opposite the handling element for at least one process step during the processing of the substrate surface, and wherein a second process-step-dependent covering element is assigned to the side of the base element opposite the handling element for at least another process step during the processing of the substrate surface.

23. (Previously Presented) The workpiece carrier according to claim 22, wherein the base element includes individual carrier elements, and wherein the substrate includes a contact surface against which the carrier elements rest.

24. (Previously Presented) The workpiece carrier according to claim 23, wherein the contact surface of includes a lower edge of a collar provided around a circumference of the substrate.

25. (Previously Presented) The workpiece carrier according to claim 24, wherein the carrier elements extend into a location hole in the base element.

26. (Previously Presented) The workpiece carrier according to claim 25, wherein the substrate is positioned on the carrier elements of the base element so that at least one opening extends between one edge of the location hole in the base element and a side wall of the substrate.

27. (Previously Presented) The workpiece carrier according to claim 26, wherein the location hole in the base element includes a hexagonal structure.

28. (Previously Presented) The workpiece carrier according to claim 22, wherein the base element and the substrate each include at least one complementary positioning element configured to fix the substrate in a relative spatial position.

29. (Previously Presented) The workpiece carrier according to claim 28, wherein the plurality substrate includes a groove provided in a side wall of the substrate, and the base element includes a complementary lug.

30. (Previously Presented) The workpiece carrier according to claim 29, wherein the groove is arranged against a lower edge of a collar provided around a circumference of the substrate, and the complementary lug extends into a location hole in the base element.

31. (Previously Presented) The workpiece carrier according to claim 22, further comprising an arrangement configured to position the handling element and the covering elements relative to one another.

32. (Previously Presented) The workpiece carrier according to claim 31, wherein the arrangement includes one of guide pins, turn-lock fasteners, expansion pins and mechanical stops.

33. (Previously Presented) The workpiece carrier according to claim 22, wherein a coding arrangement is assigned to at least one of the handling element and the covering elements.

34. (Previously Presented) The workpiece carrier according to claim 33, wherein the coding arrangement includes one of notches, bar codes and holes on a surface of the handling element.

35. (Previously Presented) The workpiece carrier according to claim 22, wherein the covering element includes individual supporting elements, and the substrate includes a supporting surface against which the supporting elements rest.

36. (Previously Presented) The workpiece carrier according to claim 35, wherein the supporting surface includes an upper edge of a collar provided around a circumference of the substrate.

37. (Previously Presented) The workpiece carrier according to claim 22, wherein the covering element includes process areas configured to allow selective treatment of a substrate surface.

38. (Previously Presented) The workpiece carrier according to claim 37, wherein the process areas of the covering element are configured to be positioned on the substrate during treatment with liquid media so that they are located above openings between the base elements and the substrates.

39. (Previously Presented) The workpiece carrier according to claim 38, wherein the process areas of the covering element includes a hexagonal structure.

40. (Previously Presented) The workpiece carrier according to claim 37, wherein the process areas of the covering element area configured to be positioned on the substrate during treatment of the substrate surface by one of precipitation,

plasma etching, photolithography and passivation so that the covering element forms a seal with a circumferential edge of the substrate surface.

41. (Currently Amended) The workpiece carrier according to claim 22, wherein the workpiece carrier holds the substrates during the substrate includes a processing of thin-film substrate substrates.

42. (Withdrawn) A substrate, comprising:
a substrate surface, the substrate essentially rotationally symmetric and configured to be positioned during a processing of the substrate surface in a holder of a workpiece carrier, the substrate and the workpiece carrier each including at least one complementary positioning element configured to fix a relative spatial position of the substrate, a positioning configured to be fixed by a holding of a rotational position of the substrate.

43. (Withdrawn) The substrate according to claim 42, wherein the substrate includes one of a groove and a notch.

44. (Withdrawn) The substrate according to claim 42, wherein the substrate includes a thin-film substrate.